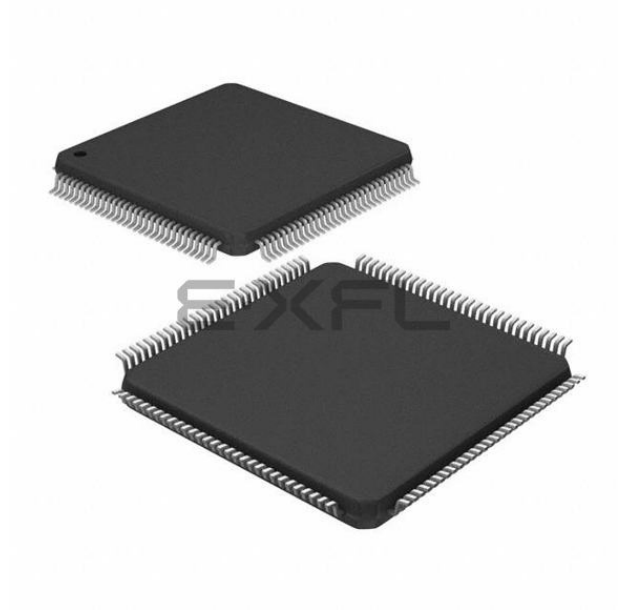
Rohm Semiconductor - ML610Q411P-NNNTB03A7 Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	nX-U8/100
Core Size	8-Bit
Speed	625kHz
Connectivity	I²C, SSP, UART/USART
Peripherals	LCD, POR, PWM, WDT
Number of I/O	22
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.1V ~ 3.6V
Data Converters	A/D 2x12b, 2x24b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	120-TQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/rohm-semi/ml610q411p-nnntb03a7

- Watchdog timer
  – Non-maskable interrupt and reset
  – Free running
  – Overflow period: 4 types selectable (125ms, 500ms, 2s, and 8s)

- Timers
  – 8 bits × 4 channels (Timer0-3: 16-bit x 2 configuration available by using Timer0-1 or Timer2-3)
  – Clock frequency measurement mode (in one channel of 16-bit configuration using Timer2-3)

- 1 kHz timer
  – 10 Hz/1 Hz interrupt function

- Capture
  – Time base capture × 2 channels (4096 Hz to 32 Hz)

- PWM
  – Resolution 16 bits × 1 channel

- Synchronous serial port
  – Master/slave selectable
  – LSB first/MSB first selectable
  – 8-bit length/16-bit length selectable

- UART
  – TXD/RXD × 1 channel
  – Bit length, parity/no parity, odd parity/even parity, 1 stop bit/2 stop bits
  – Positive logic/negative logic selectable
  – Built-in baud rate generator

- I^2C bus interface
  – Master function only
  – Standard mode (50kbps)

- Buzzer driver
  – 4 output modes, 8 frequencies, 16 duty levels

- RC oscillation type A/D converter
  – 24-bit counter
  – Time division × 2 channels

- Successive approximation type A/D converter
  – 12-bit A/D converter
  – Input × 2 channels
  – Conversion time: 46us/1ch@500kHz

- General-purpose ports
  – Non-maskable interrupt input port × 1 channel
  – Input-only port × 6 channels (including secondary functions)
  – Output-only port × 3 channels (including secondary functions)
  – Input/output port
    ML610Q411: 22 channels (including secondary functions)
    ML610Q412: 14 channels (including secondary functions)

- LCD driver
  – The number of segments
    ML610Q411: 144 dots max. (36 seg × 4 com)
    ML610Q412: 176 dots max. (44 seg × 4 com)
  – 1/1 to 1/4 duty
  – 1/3 bias (built-in bias generation circuit)

BLOCK DIAGRAM

ML610Q411 Block Diagram

Figure 1 show the block diagram of the ML610Q411.
"*" indicates the secondary function of each port.

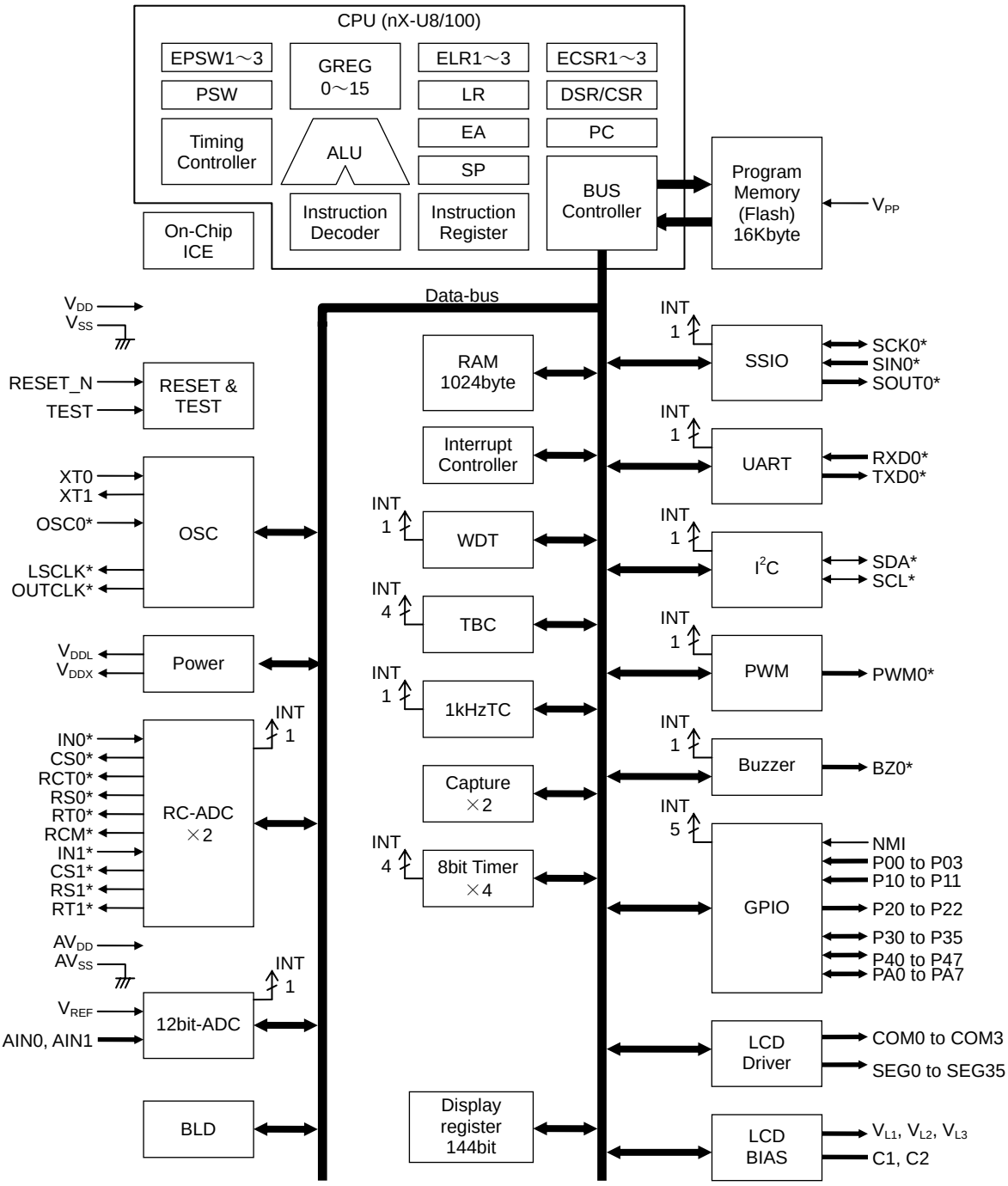
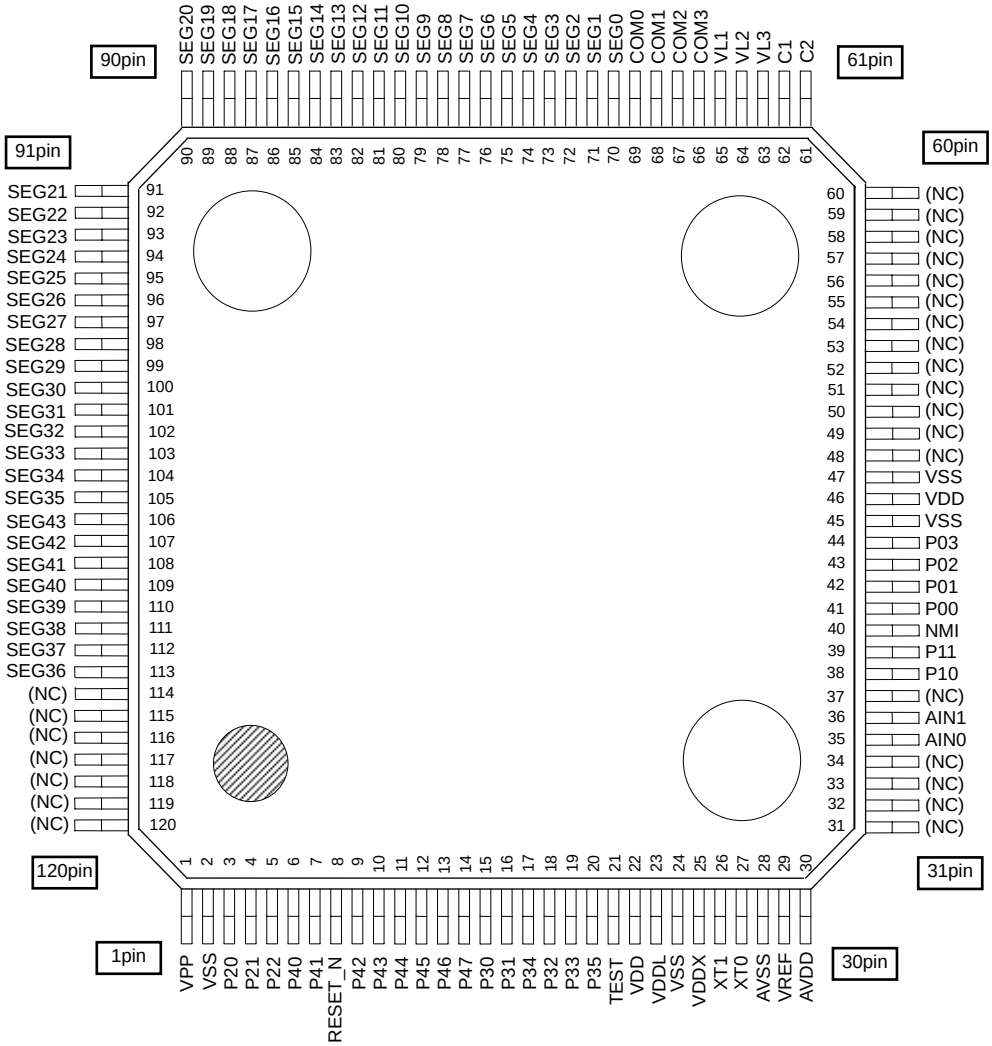


Figure 1 ML610Q411 Block Diagram

ML610Q412 TQFP120 Pin Layout

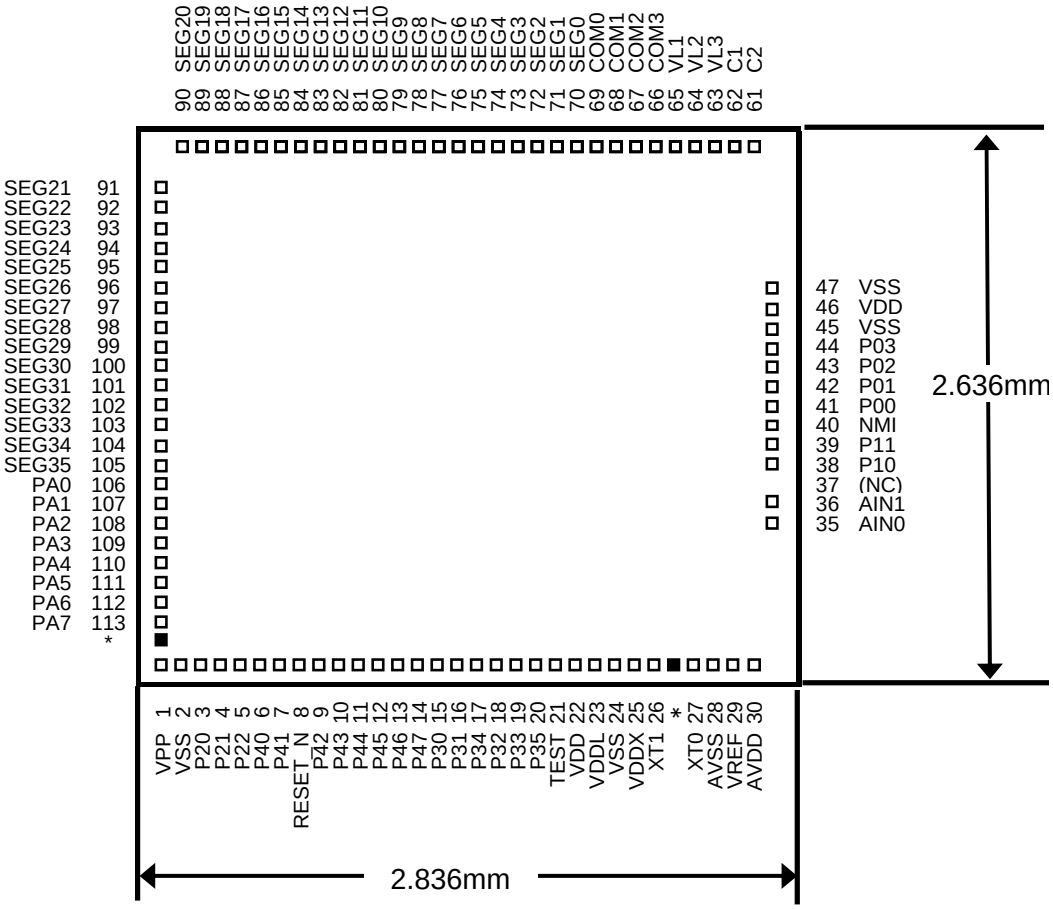


(NC): No Connection

Note:
The assignment of the P30 to P35 are not in order.

Figure 4 ML610Q412 TQFP120 Pin Configuration

ML610Q411 Chip Pin Layout & Dimension

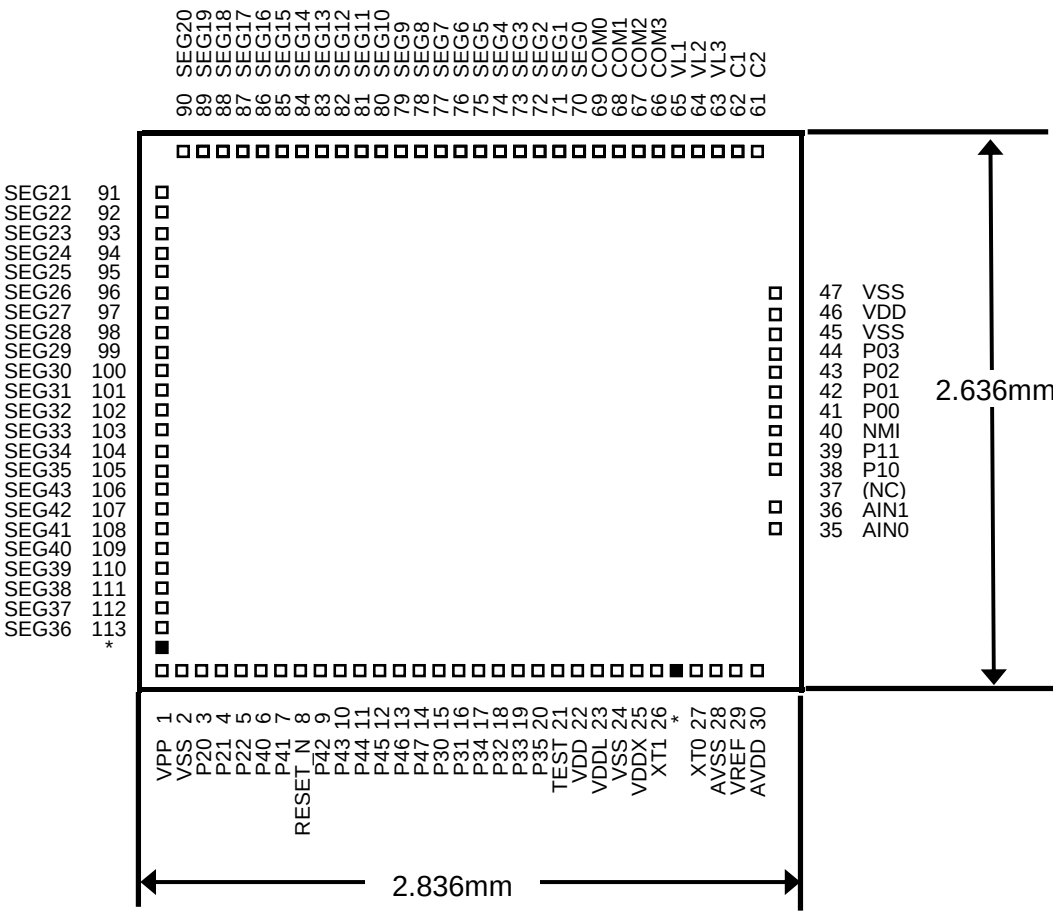


* Dummy pad
Note: These dummy pads are visible and do have any function, they are placed for a mechanical evaluation in LAPIS Semiconductor. Please do NOT implement wire-bonding to the dummy pad.

Chip size:	2.836mm x 2.636mm
PAD count:	95 pins
Minimum PAD pitch:	80 μm
PAD aperture:	70 μm × 70 μm
Chip thickness:	350 μm
Voltage of the rear side of chip:	V_{SS} level

Figure 5 ML610Q411 Chip Layout & Dimension

ML610Q412 Chip Pin Layout & Dimension



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Chip thickness:	350 μm
Voltage of the rear side of chip:	V_{SS} level

Figure 6 ML610Q412 Chip Layout & Dimension

ML610Q411 Pad Coordinates

Table 1 ML610Q411 Pad Coordinates

Chip Center: X=0,Y=0

PAD No.	Pad Name	X (µm)	Y (µm)	PAD No.	Pad Name	X (µm)	Y (µm)	PAD No.	Pad Name	X (µm)	Y (µm)
1	VPP	-1230	-1212	51	(NC)	-	-	101	SEG31	-1312	160
2	VSS	-1150	-1212	52	(NC)	-	-	102	SEG32	-1312	80
3	P20	-1070	-1212	53	(NC)	-	-	103	SEG33	-1312	0
4	P21	-990	-1212	54	(NC)	-	-	104	SEG34	-1312	-80
5	P22	-910	-1212	55	(NC)	-	-	105	SEG35	-1312	-160
6	P40	-830	-1212	56	(NC)	-	-	106	PA0	-1312	-240
7	P41	-750	-1212	57	(NC)	-	-	107	PA1	-1312	-320
8	RESET_N	-670	-1212	58	(NC)	-	-	108	PA2	-1312	-400
9	P42	-590	-1212	59	(NC)	-	-	109	PA3	-1312	-480
10	P43	-510	-1212	60	(NC)	-	-	110	PA4	-1312	-560
11	P44	-430	-1212	61	C2	1220	1212	111	PA5	-1312	-640
12	P45	-350	-1212	62	C1	1140	1212	112	PA6	-1312	-720
13	P46	-270	-1212	63	VL3	1060	1212	113	PA7	-1312	-800
14	P47	-190	-1212	64	VL2	980	1212	--	Dummy	-1312	-908
15	P30	-110	-1212	65	VL1	900	1212				
16	P31	-30	-1212	66	COM3	820	1212				
17	P34	50	-1212	67	COM2	740	1212				
18	P32	130	-1212	68	COM1	660	1212				
19	P33	210	-1212	69	COM0	580	1212				
20	P35	290	-1212	70	SEG0	500	1212				
21	TEST	370	-1212	71	SEG1	420	1212				
22	VDD	450	-1212	72	SEG2	340	1212				
23	VDDL	530	-1212	73	SEG3	260	1212				
24	VSS	610	-1212	74	SEG4	180	1212				
25	VDDX	690	-1212	75	SEG5	100	1212				
26	XT1	770	-1212	76	SEG6	20	1212				
-	Dummy	850	-1212	77	SEG7	-60	1212				
27	XT0	930	-1212	78	SEG8	-140	1212				
28	AVSS	1030	-1212	79	SEG9	-220	1212				
29	VREF	1110	-1212	80	SEG10	-300	1212				
30	AVDD	1190	-1212	81	SEG11	-380	1212				
31	(NC)	-	-	82	SEG12	-460	1212				
32	(NC)	-	-	83	SEG13	-540	1212				
33	(NC)	-	-	84	SEG14	-620	1212				
34	(NC)	-	-	85	SEG15	-700	1212				
35	AIN0	1312	-522	86	SEG16	-780	1212				
36	AIN1	1312	-350	87	SEG17	-860	1212				
37	(NC)	-	-	88	SEG18	-940	1212				
38	P10	1312	-210	89	SEG19	-1020	1212				
39	P11	1312	-130	90	SEG20	-1100	1212				
40	NMI	1312	-50	91	SEG21	-1312	960				
41	P00	1312	30	92	SEG22	-1312	880				
42	P01	1312	110	93	SEG23	-1312	800				
43	P02	1312	190	94	SEG24	-1312	720				
44	P03	1312	270	95	SEG25	-1312	640				
45	VSS	1312	350	96	SEG26	-1312	560				
46	VDD	1312	430	97	SEG27	-1312	480				
47	VSS	1312	510	98	SEG28	-1312	400				
48	(NC)	-	-	99	SEG29	-1312	320				
49	(NC)	-	-	100	SEG30	-1312	240				
50	(NC)	-	-								

PIN LIST

PAD No.	Primary function			Secondary function			Tertiary function		
	Pin name	I/O	Function	Pin name	I/O	Function	Pin name	I/O	Function
2, 24,45,47	V_{SS}	—	Negative power supply pin	—	—	—	—	—	—
22, 46	V_{DD}	—	Positive power supply pin	—	—	—	—	—	—
23	V_{DDL}	—	Power supply pin for internal logic (internally generated)	—	—	—	—	—	—
25	V_{DDX}	—	Power supply pin for low-speed oscillation (internally generated)	—	—	—	—	—	—
1	V_{PP}	—	Power supply pin for Flash ROM	—	—	—	—	—	—
28	AV_{SS}	—	Negative power supply pin for successive approximation type ADC	—	—	—	—	—	—
30	AV_{DD}	—	Positive power supply pin for successive approximation type ADC	—	—	—	—	—	—
65	V_{L1}	—	Power supply pin for LCD bias (internally generated)	—	—	—	—	—	—
64	V_{L2}	—	Power supply pin for LCD bias (internally generated)	—	—	—	—	—	—
63	V_{L3}	—	Power supply pin for LCD bias (internally generated)	—	—	—	—	—	—
62	C1	—	Capacitor connection pin for LCD bias generation	—	—	—	—	—	—
61	C2	—	Capacitor connection pin for LCD bias generation	—	—	—	—	—	—
21	TEST	I/O	Input/output pin for testing	—	—	—	—	—	—
8	RESET_N	I	Reset input pin	—	—	—	—	—	—
27	XT0	I	Low-speed clock oscillation pin	—	—	—	—	—	—
26	XT1	O	Low-speed clock oscillation pin	—	—	—	—	—	—
29	V_{REF}	—	Reference power supply pin for successive approximation type ADC	—	—	—	—	—	—

PAD No.	Primary function			Secondary function			Tertiary function		
	Pin name	I/O	Function	Pin name	I/O	Function	Pin name	I/O	Function
35	AIN0	I	Successive approximation type ADC input	—	—	—	—	—	—
36	AIN1	I	Successive approximation type ADC input	—	—	—	—	—	—
40	NMI	I	Non-maskable interrupt pin	—	—	—	—	—	—
41	P00/EXI0/ CAP0	I	Input port, External interrupt 0, Capture 0 input	—	—	—	—	—	—
42	P01/EXI1/ CAP1	I	Input port, External interrupt 1, Capture 1 input	—	—	—	—	—	—
43	P02/EXI2/ RXD0	I	Input port, External interrupt 2, UART0 receive	—	—	—	—	—	—
44	P03/EXI3	I	Input port, External interrupt 3	—	—	—	—	—	—
38	P10 OSC0	I	Input port External clock input	—	—	—	—	—	—
39	P11	I	Input port	—	—	—	—	—	—
3	P20/LED0	O	Output port	LSCLK	O	Low-speed clock output	—	—	—
4	P21LED1	O	Output port	OUTCLK	O	High-speed clock output	—	—	—
5	P22/LED2	O	Output port	MD0	O	Melody output	—	—	—
15	P30	I/O	Input/output port	IN0	I	RC type ADC0 oscillation input pin	—	—	—
16	P31	I/O	Input/output port	CS0	O	RC type ADC0 reference capacitor connection pin	—	—	—
17	P34	I/O	Input/output port	RCT0	O	RC type ADC0 resistor/capacitor sensor connection pin	PWM0	O	PWM output
18	P32	I/O	Input/output port	RS0	O	RC type ADC0 reference resistor connection pin	—	—	—
19	P33	I/O	Input/output port	RT0	O	RC type ADC0 resistor sensor connection pin	—	—	—
20	P35	I/O	Input/output port	RCM	O	RC type ADC oscillation monitor	—	—	—
6	P40	I/O	Input/output port	SDA	I/O	I^2C data input/output	SIN0	I	SSIO data input
7	P41	I/O	Input/output port	SCL	I/O	I^2C clock input/output	SCK0	I/O	SSIO synchronous clock
9	P42	I/O	Input/output port	RXD0	I	UART data input	SOUT0	I	SSIO data output
10	P43	I/O	Input/output port	TXD0	O	UART data output	PWM0	O	PWM output
11	P44/T02P0 CK	I/O	Input/output port, Timer 0/Timer 2/PWM0 external clock input	IN1	I	RC type ADC1 oscillation input pin	SIN0	I	SSIO0 data input
12	P45/T13P1 CK	I/O	Input/output port, Timer 1/Timer 3 external clock input	CS1	O	RC type ADC1 reference capacitor connection pin	SCK0	I/O	SSIO0 synchronous clock
13	P46	I/O	Input/output port	RS1	O	RC type ADC1 reference resistor connection pin	SOUT0	O	SSIO0 data output
14	P47	I/O	Input/output port	RT1	O	RC type ADC1 resistor sensor connection pin	—	—	—
106	PA0(*1)	I/O	Input/output port	—	—	—	—	—	—
	SEG43(*2)	O	LCD segment pin	—	—	—	—	—	—
107	PA1(*1)	I/O	Input/output port	—	—	—	—	—	—
	SEG42(*2)	O	LCD segment pin	—	—	—	—	—	—
108	PA2(*1)	I/O	Input/output port	—	—	—	—	—	—
	SEG41(*2)	O	LCD segment pin	—	—	—	—	—	—
109	PA3(*1)	I/O	Input/output port	—	—	—	—	—	—
	SEG40(*2)	O	LCD segment pin	—	—	—	—	—	—

PAD No.	Primary function			Secondary function			Tertiary function		
	Pin name	I/O	Function	Pin name	I/O	Function	Pin name	I/O	Function
110	PA4(*1)	I/O	Input/output port	—	—	—	—	—	—
	SEG39(*2)	O	LCD segment pin	—	—	—	—	—	—
111	PA5(*1)	I/O	Input/output port	—	—	—	—	—	—
	SEG38(*2)	O	LCD segment pin	—	—	—	—	—	—
112	PA6(*1)	I/O	Input/output port	—	—	—	—	—	—
	SEG37(*2)	O	LCD segment pin	—	—	—	—	—	—
113	PA7(*1)	I/O	Input/output port	—	—	—	—	—	—
	SEG36(*2)	O	LCD segment pin	—	—	—	—	—	—
69	COM0	O	LCD common pin	—	—	—	—	—	—
68	COM1	O	LCD common pin	—	—	—	—	—	—
67	COM2	O	LCD common pin	—	—	—	—	—	—
66	COM3	O	LCD common pin	—	—	—	—	—	—
70	SEG0	O	LCD segment pin	—	—	—	—	—	—
71	SEG1	O	LCD segment pin	—	—	—	—	—	—
72	SEG2	O	LCD segment pin	—	—	—	—	—	—
73	SEG3	O	LCD segment pin	—	—	—	—	—	—
74	SEG4	O	LCD segment pin	—	—	—	—	—	—
75	SEG5	O	LCD segment pin	—	—	—	—	—	—
76	SEG6	O	LCD segment pin	—	—	—	—	—	—
77	SEG7	O	LCD segment pin	—	—	—	—	—	—
78	SEG8	O	LCD segment pin	—	—	—	—	—	—
79	SEG9	O	LCD segment pin	—	—	—	—	—	—
80	SEG10	O	LCD segment pin	—	—	—	—	—	—
81	SEG11	O	LCD segment pin	—	—	—	—	—	—
82	SEG12	O	LCD segment pin	—	—	—	—	—	—
83	SEG13	O	LCD segment pin	—	—	—	—	—	—
84	SEG14	O	LCD segment pin	—	—	—	—	—	—
85	SEG15	O	LCD segment pin	—	—	—	—	—	—
86	SEG16	O	LCD segment pin	—	—	—	—	—	—
87	SEG17	O	LCD segment pin	—	—	—	—	—	—
88	SEG18	O	LCD segment pin	—	—	—	—	—	—
89	SEG19	O	LCD segment pin	—	—	—	—	—	—
90	SEG20	O	LCD segment pin	—	—	—	—	—	—
91	SEG21	O	LCD segment pin	—	—	—	—	—	—
92	SEG22	O	LCD segment pin	—	—	—	—	—	—
93	SEG23	O	LCD segment pin	—	—	—	—	—	—
94	SEG24	O	LCD segment pin	—	—	—	—	—	—
95	SEG25	O	LCD segment pin	—	—	—	—	—	—
96	SEG26	O	LCD segment pin	—	—	—	—	—	—
97	SEG27	O	LCD segment pin	—	—	—	—	—	—
98	SEG28	O	LCD segment pin	—	—	—	—	—	—
99	SEG29	O	LCD segment pin	—	—	—	—	—	—
100	SEG30	O	LCD segment pin	—	—	—	—	—	—
101	SEG31	O	LCD segment pin	—	—	—	—	—	—
102	SEG32	O	LCD segment pin	—	—	—	—	—	—
103	SEG33	O	LCD segment pin	—	—	—	—	—	—
104	SEG34	O	LCD segment pin	—	—	—	—	—	—
105	SEG35	O	LCD segment pin	—	—	—	—	—	—

(*1) Pins on ML610Q411.
(*2) Pins on ML610Q412.

Pin name	I/O	Description	Primary/ Secondary/ Tertiary	Logic
UART				
TXD0	O	UART data output pin. This pin is used as the secondary function of the P43 pin.	Secondary	Positive
RXD0	I	UART data input pin. This pin is used as the secondary function of the P42 or the primary function of the P02 pin.	Primary/Secondary	Positive
I^2C bus interface				
SDA	I/O	I^2C data input/output pin. This pin is used as the secondary function of the P40 pin. This pin has an NMOS open drain output. When using this pin as a function of the I^2C, externally connect a pull-up resistor.	Secondary	Positive
SCL	O	I^2C clock output pin. This pin is used as the secondary function of the P41 pin. This pin has an NMOS open drain output. When using this pin as a function of the I^2C, externally connect a pull-up resistor.	Secondary	Positive
Synchronous serial (SSIO)				
SCK0	I/O	Synchronous serial clock input/output pin. This pin is used as the tertiary function of the P41 or P45 pin.	Tertiary	—
SIN0	I	Synchronous serial data input pin. This pin is used as the tertiary function of the P40 or P44 pin.	Tertiary	Positive
SOUT0	O	Synchronous serial data output pin. This pin is used as the tertiary function of the P42 or P46 pin.	Tertiary	Positive
PWM				
PWM0	O	PWM0 output pin. This pin is used as the tertiary function of the P43 or P34 pin.	Tertiary	Positive
T02P0CK	O	PWM0 external clock input pin. This pin is used as the primary function of the P44 pin.	Primary	—
External interrupt				
NMI	I	External non-maskable interrupt input pin. An interrupt is generated on both edges.	Primary	Positive/ negative
EXI0-3	I	External maskable interrupt input pins. Interrupt enable and edge selection can be performed for each bit by software. These pins are used as the primary functions of the P00-P03 pins.	Primary	Positive/ negative
Capture				
CAP0	I	Capture trigger input pins. The value of the time base counter is captured in the register synchronously with the interrupt edge selected by software. These pins are used as the primary functions of the P00 pin(CAP0) and P01 pin(CAP1).	Primary	Positive/ negative
CAP1	I		Primary	Positive/ negative
Timer				
T02P0CK	I	External clock input pin used for both Timer 0 and Timer 2. The clocks for these timers are selected by software. This pin is used as the primary function of the P44 pin.	Primary	—
T13P1CK	I	External clock input pin used for both Timer 1 and Timer 3. The clocks for these timers are selected by software. This pin is used as the primary function of the P45 pin.	Primary	—
Buzzer				
BZ0	O	Buzzer signal output pin. This pin is used as the secondary function of the P22 pin.	Secondary	Positive/ negative
LED drive				
LED0-2	O	Nch open drain output pins to drive LED.	Primary	Positive/ negative

ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS

(V_{SS} = AV_{SS} = 0V)

Parameter	Symbol	Condition	Rating	Unit
Power supply voltage 1	V_{DD}	Ta = 25°C	–0.3 to +4.6	V
Power supply voltage 2	AV_{DD}	Ta = 25°C	–0.3 to +4.6	V
Power supply voltage 3	V_{PP}	Ta = 25°C	–0.3 to +9.5	V
Power supply voltage 4	V_{DDL}	Ta = 25°C	–0.3 to +3.6	V
Power supply voltage 5	V_{DDX}	Ta = 25°C	–0.3 to +3.6	V
Power supply voltage 6	V_{L1}	Ta = 25°C	–0.3 to +1.75	V
Power supply voltage 7	V_{L2}	Ta = 25°C	–0.3 to +3.5	V
Power supply voltage 8	V_{L3}	Ta = 25°C	–0.3 to +5.25	V
Input voltage	V_{IN}	Ta = 25°C	–0.3 to V_{DD}+0.3	V
Output voltage	V_{OUT}	Ta = 25°C	–0.3 to V_{DD}+0.3	V
Output current 1	I_{OUT1}	Port3–A, Ta = 25°C	–12 to +11	mA
Output current 2	I_{OUT2}	Port2, Ta = 25°C	–12 to +20	mA
Power dissipation	PD	Ta = 25°C	1.25	W
Storage temperature	T_{STG}	—	–55 to +150	°C

RECOMMENDED OPERATING CONDITIONS

(V_{SS} = AV_{SS} = 0V)

Parameter	Symbol	Condition	Range	Unit
Operating temperature	T_{OP}	ML610Q411, ML610Q412,	–20 to +70	°C
		ML610Q411P, ML610Q411PA, ML610Q412P	–40 to +85	
Operating voltage	V_{DD}	—	1.1 to 3.6	V
	AV_{DD}	—	2.2 to 3.6	
Operating frequency (CPU)	f_{OP}	V_{DD} = 1.1 to 3.6V	30k to 36k 46.9k to 78.1k	Hz
		V_{DD} = 1.3 to 3.6V	30k to 625k	
			23k to 625k	
Capacitor externally connected to V_{DDL} pin	C_{L0}	—	1.0±30%	µF
	C_{L1}	—	0.1±30%	
Capacitor externally connected to V_{DDX} pin	C_X	—	0.1±30%	µF
Capacitors externally connected to $V_{L1, 2, 3}$ pins	$C_{1, 2, 3}$	—	1.0±30%	µF
Capacitors externally connected across C1 and C2 pins	C_{12}	—	1.0±30%	µF

CLOCK GENERATION CIRCUIT OPERATING CONDITIONS

(V_{SS} = 0V)

Parameter	Symbol	Condition	Rating			Unit
			Min.	Typ.	Max.	
Low-speed crystal oscillation frequency	f_{XTL}	—	—	32.768k	—	Hz
Recommended equivalent series resistance value of low-speed crystal oscillation	R_L	—	—	—	40k	Ω
Low-speed crystal oscillation external capacitor [*1]	C_{DL}/C_{GL}	C_L=6pF of crystal oscillation [*2]	—	0	—	pF
		C_L=9pF of crystal oscillation	—	6	—	
		C_L=12pF of crystal oscillation	—	12	—	
	C_{GH}	—	—	24	—	

[*1]: The external C_{DL} and C_{GL} need to be adjusted in consideration of variation of internal loading capacitance C_D and C_G, and other additional capacitance such as PCB layout.

[*2]: When using a crystal oscillator C_L = 6pF, there is a possibility that can not be adjusted by external C_{DL} and C_{GL}.

OPERATING CONDITIONS OF FLASH ROM

(V_{SS} = AV_{SS} = 0V)

Parameter	Symbol	Condition	Range	Unit
Operating temperature	T_{OP}	At write/erase	0 to +40	°C
Operating voltage	V_{DD}	At write/erase[*1]	2.75 to 3.6	V
	V_{DDL}	At write/erase[*1]	2.5 to 2.75	
	V_{PP}	At write/erase[*1]	7.7 to 8.3	
Write cycles	C_{EP}	—	80	cycles
Data retention	Y_{DR}	—	10	years

[*1]: Those voltages must be supplied to V_{DDL} pin and V_{PP} pin when programming and eraseing Flash ROM. V_{PP} pin has an internal pulldown resister.

DC CHARACTERISTICS (2/5)

(V_{DD} = 1.1 to 3.6V, AV_{DD} = 2.2 to 3.6V, V_{SS} = AV_{SS} = 0V, Ta = –20 to +70°C, Ta = –40 to +85°C for P version, unless otherwise specified) (2/5)

Parameter	Symbol	Condition		Rating Min.	Rating Typ.	Rating Max.	Unit	Measuring circuit
V_{L1} voltage	V_{L1}	V_{DD} = 3.0V, Tj = 25°C	CN4–0 = 00H	0.89	0.94	0.99	V	1
			CN4–0 = 01H	0.91	0.96	1.01		
			CN4–0 = 02H	0.93	0.98	1.03		
			CN4–0 = 03H	0.95	1.00	1.05		
			CN4–0 = 04H	0.97	1.02	1.07		
			CN4–0 = 05H	0.99	1.04	1.09		
			CN4–0 = 06H	1.01	1.06	1.11		
			CN4–0 = 07H	1.03	1.08	1.13		
			CN4–0 = 08H	1.05	1.10	1.15		
			CN4–0 = 09H	1.07	1.12	1.17		
			CN4–0 = 0AH	1.09	1.14	1.19		
			CN4–0 = 0BH	1.11	1.16	1.21		
			CN4–0 = 0CH	1.13	1.18	1.23		
			CN4–0 = 0DH	1.15	1.20	1.25		
			CN4–0 = 0EH	1.17	1.22	1.27		
			CN4–0 = 0FH	1.19	1.24	1.29		
			CN4–0 = 10H	1.21	1.26	1.31		
			CN4–0 = 11H	1.23	1.28	1.33		
			CN4–0 = 12H	1.25	1.30	1.35		
			CN4–0 = 13H	1.27	1.32	1.37		
			CN4–0 = 14H	1.29	1.34	1.39		
			CN4–0 = 15H	1.31	1.36	1.41		
			CN4–0 = 16H	1.33	1.38	1.43		
			CN4–0 = 17H	1.35	1.40	1.45		
			CN4–0 = 18H	1.37	1.42	1.47		
			CN4–0 = 19H	1.39	1.44	1.49		
			CN4–0 = 1AH	1.41	1.46	1.51		
			CN4–0 = 1BH	1.43	1.48	1.53		
			CN4–0 = 1CH	1.45	1.50	1.55		
			CN4–0 = 1DH	1.47	1.52	1.57		
			CN4–0 = 1EH	1.49	1.54	1.59		
			CN4–0 = 1FH	1.51	1.56	1.61		
V_{L1} temperature deviation *1	ΔV_{L1}	V_{DD} = 3.0V		—	–1.5	—	mV/°C	
V_{L1} voltage dependency *1	ΔV_{L1}	V_{DD} = 1.3 to 3.6V		—	5	20	mV/V	
V_{L2} voltage	V_{L2}	V_{DD} = 3.0V, Tj = 25°C 1MΩ load (V_{L3}–V_{SS})		Typ. –10%	V_{L1}×2	Typ. +4%	V	
V_{L3} voltage	V_{L3}			Typ. –10%	V_{L1}×3	Typ. +4%		
LCD bias voltage generation time	T_{BIAS}	—		—	—	600	ms	

*1:V_{L1} can not exceed V_{DD} level. The maximum V_{L1} becomes V_{DD} level when the V_{L1} calculated by the temperature deviation and voltage dependency is going to exceed the V_{DD} level.

DC CHARACTERISTICS (3/5)

(V_{DD} = 1.1 to 3.6V, AV_{DD} = 2.2 to 3.6V, V_{SS} = AV_{SS} = 0V, Ta = –20 to +70°C, Ta = –40 to +85°C for P version, unless otherwise specified) (3/5)

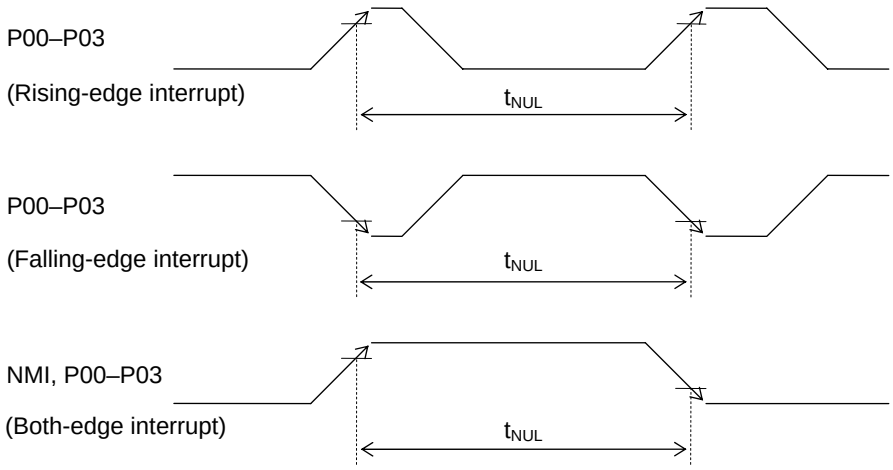
Parameter	Symbol	Condition		Rating Min.	Rating Typ.	Rating Max.	Unit	Measuring circuit
BLD threshold voltage	V_{BLD}	V_{DD} = 1.35 to 3.6V	LD3–0 = 0H	Typ. –2%	1.35	Typ. +2%	V	1
			LD3–0 = 1H		1.4			
			LD3–0 = 2H		1.45			
			LD3–0 = 3H		1.5			
			LD3–0 = 4H		1.6			
			LD3–0 = 5H		1.7			
			LD3–0 = 6H		1.8			
			LD3–0 = 7H		1.9			
			LD3–0 = 8H		2.0			
			LD3–0 = 9H		2.1			
			LD3–0 = 0AH		2.2			
			LD3–0 = 0BH		2.3			
			LD3–0 = 0CH		2.4			
			LD3–0 = 0DH		2.5			
			LD3–0 = 0EH		2.7			
			LD3–0 = 0FH		2.9			
BLD threshold voltage temperature deviation	ΔV_{BLD}	V_{DD} = 1.35 to 3.6V		—	0	—	%/°C	
Supply current 1	IDD1	CPU: In STOP state. Low-speed/high-speed RC500kHz oscillation: stopped.	Ta= 25°C	—	0.15	0.5	μA	1
			*5	—	—	2.5		
Supply current 2	IDD2	CPU: In HALT state (LTBC and WDT are Operating. Low speed oscillation stop detector is Stopped).*3*4 High-speed 500kHz oscillation: Stopped. LCD and BIAS circuits: Stopped.	Ta= 25°C	—	0.5	1.3	μA	
			*5	—	—	3.5		
Supply current 3	IDD3	CPU: In HALT state (LTBC and WDT are Operating. Low speed oscillation stop detector is Stopped).*3 High-speed 500kHz oscillation: Stopped. LCD and BIAS circuits: Operating. *2	Ta= 25°C	—	1.28	1.6	μA	
			*5	—	—	11		
Supply current 4	IDD4	CPU: In 32.768kHz operating state.*1*3 High-speed 500kHz oscillation: Stopped. LCD and BIAS circuits: Operating. *2	Ta= 25°C	—	5.5	7	μA	
			*5	—	—	12		
Supply current 5	IDD5	CPU: In RC 500kHz operating state. LCD and BIAS circuits: Operating. *2	Ta= 25°C	—	80	90	μA	1
			*5	—	—	100		
Supply current 6	IDD6	CPU: In RC 500kHz operating state.*2 LCD and BIAS circuits: Operating. *2 A/D: In operating state. V_{DD} = AV_{DD} = 3.0V	Ta= 25°C	—	0.4	0.5	mA	
			*5	—	—	0.6		

*1: When the CPU operating rate is 100% (No HALT state).
*2: All SEGs: off waveform, No LCD panel load, 1/3 bias, 1/3 duty, Frame frequency: Approx. 64 Hz, Bias voltage multiplying clock: 1/128 LSCLK (256Hz)
*3 : Use 32.768KHz Crystal Oscillator C-001R (Epson Toyocom) with capacitance C_{GL}/C_{DL}=0pF.
*4 : Significant bits of BLKCON0~BLKCON4 registers are all "1".
*5 : Recommended operating temperature (Ta = –40 to +85°C for P version, Ta = –20 to +70°C for non-P version)

AC CHARACTERISTICS (External Interrupt)

(V_{DD} = 1.1 to 3.6V, AV_{DD} = 2.2 to 3.6V, V_{SS} = AV_{SS} = 0V, Ta = –20 to +70°C, Ta = –40 to +85°C for P version, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit
			Min.	Typ.	Max.	
External interrupt disable period	T_{NUL}	Interrupt: Enabled (MIE = 1), CPU: NOP operation System clock: 32.768kHz	76.8	—	106.8	µs

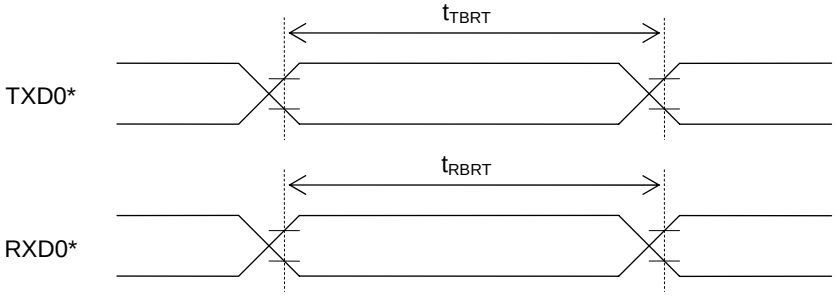


AC CHARACTERISTICS (Serial Port)

(V_{DD} = 1.3 to 3.6V, AV_{DD} = 2.2 to 3.6V, V_{SS} = AV_{SS} = 0V, Ta = –20 to +70°C, Ta = –40 to +85°C for P version, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit
			Min.	Typ.	Max.	
Transmit baud rate	t_{TBRT}	—	—	BRT*[1]	—	s
Receive baud rate	t_{RBRT}	—	BRT*[1] –3%	BRT*[1]	BRT*[1] +3%	s

*1: Baud rate period (including the error of the clock frequency selected) set with the serial port baud rate register (SIOBRTL,H) and the serial port mode register 0 (SIOMOD0).

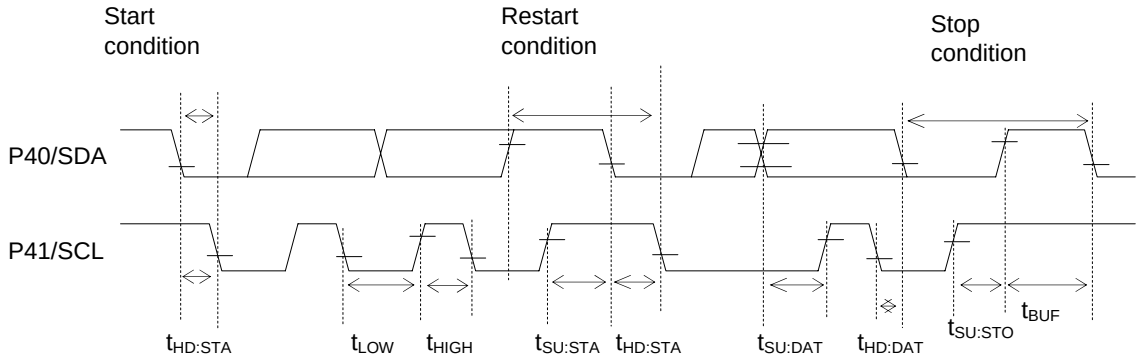


*: Indicates the secondary function of the port.

AC CHARACTERISTICS (I^2C Bus Interface: Standard Mode)

(V_{DD} = 1.8 to 3.6V, AV_{DD} = 2.2 to 3.6V, V_{SS} = AV_{SS} = 0V, Ta = –20 to +70°C, Ta = –40 to +85°C for P version, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit
			Min.	Typ.	Max.	
SCL clock frequency	f_{SCL}	—	—	50	—	kHz
SCL hold time (start/restart condition)	$t_{HD:STA}$	—	4.0	—	—	µs
SCL "L" level time	t_{LOW}	—	4.7	—	—	µs
SCL "H" level time	t_{HIGH}	—	4.0	—	—	µs
SCL setup time (restart condition)	$t_{SU:STA}$	—	4.7	—	—	µs
SDA hold time	$t_{HD:DAT}$	—	0	—	—	µs
SDA setup time	$t_{SU:DAT}$	—	0.25	—	—	µs
SDA setup time (stop condition)	$t_{SU:STO}$	—	4.0	—	—	µs
Bus-free time	t_{BUF}	—	4.7	—	—	µs



AC CHARACTERISTICS (RC Oscillation A/D Converter)

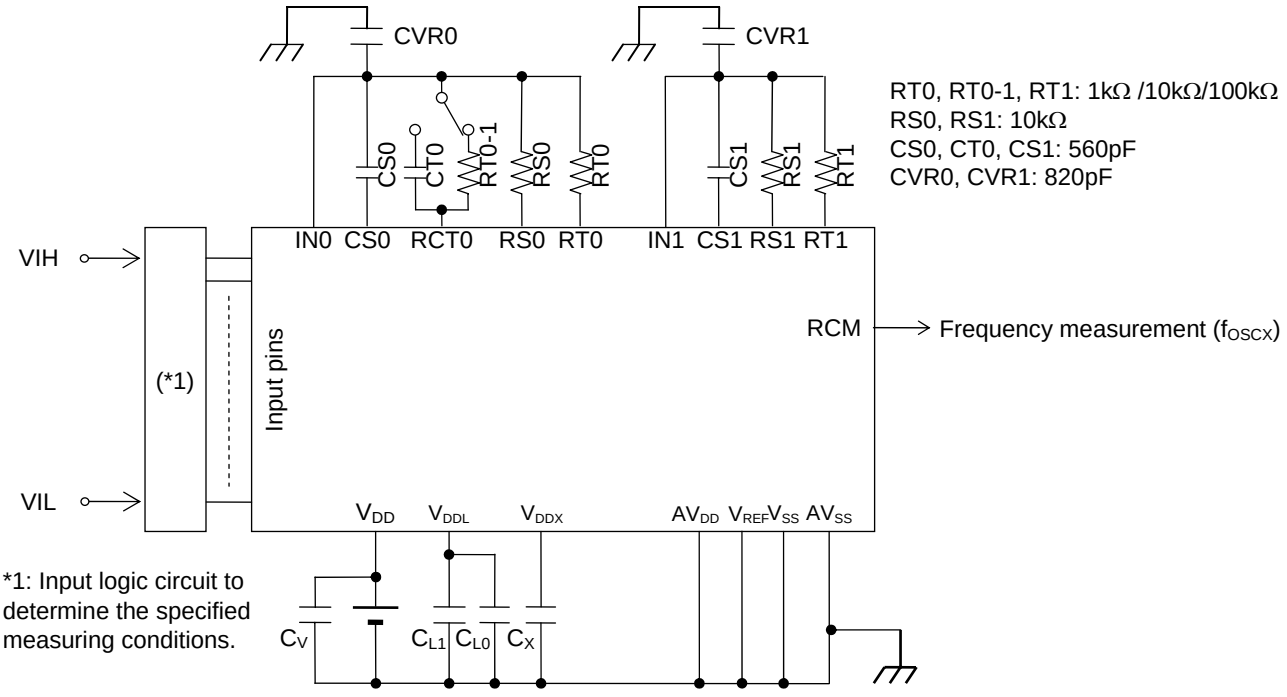
(V_{DD} = 1.3 to 3.6V, AV_{DD} = 2.2 to 3.6V, V_{SS} = AV_{SS} = 0V, Ta = –20 to +70°C, Ta = –40 to +85°C for P version, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit
			Min.	Typ.	Max.	
Resistors for oscillation	RS0, RS1, RT0, RT0-1,RT1	CS0, CT0, CS1 ≥ 740pF	1	—	—	kΩ
Oscillation frequency VDD = 1.5V	f_{OSC1}	Resistor for oscillation = 1kΩ	209.4	330.6	435.1	kHz
	f_{OSC2}	Resistor for oscillation = 10kΩ	41.29	55.27	64.16	kHz
	f_{OSC3}	Resistor for oscillation = 100kΩ	4.71	5.97	7.06	kHz
RS to RT oscillation frequency ratio *1 VDD = 1.5V	Kf1	RT0, RT0-1, RT1 = 1kHz	5.567	5.982	6.225	—
	Kf2	RT0, RT0-1, RT1 = 10kHz	0.99	1	1.01	—
	Kf3	RT0, RT0-1, RT1 = 100kHz	0.104	0.108	0.118	—
Oscillation frequency VDD = 3.0V	f_{OSC1}	Resistor for oscillation = 1kΩ	407.3	486.7	594.6	kHz
	f_{OSC2}	Resistor for oscillation = 10kΩ	49.76	59.28	72.76	kHz
	f_{OSC3}	Resistor for oscillation = 100kΩ	5.04	5.993	7.04	kHz
RS to RT oscillation frequency ratio *1 VDD = 3.0V	Kf1	RT0, RT0-1, RT1 = 1kHz	8.006	8.210	8.416	—
	Kf2	RT0, RT0-1, RT1 = 10kHz	0.99	1	1.01	—
	Kf3	RT0, RT0-1, RT1 = 100kHz	0.100	0.108	0.115	—

*1: Kfx is the ratio of the oscillation frequency by the sensor resistor to the oscillation frequency by the reference resistor on the same conditions.

$$Kfx = \frac{f_{OSCX}(RT0\text{–}CS0\ oscillation)}{f_{OSCX}(RS0\text{–}CS0\ oscillation)}, \frac{f_{OSCX}(RT0\text{-}1\text{–}CS0\ oscillation)}{f_{OSCX}(RS0\text{–}CS0\ oscillation)}, \frac{f_{OSCX}(RT1\text{–}CS1\ oscillation)}{f_{OSCX}(RS1\text{–}CS1\ oscillation)}$$

(x = 1, 2, 3)



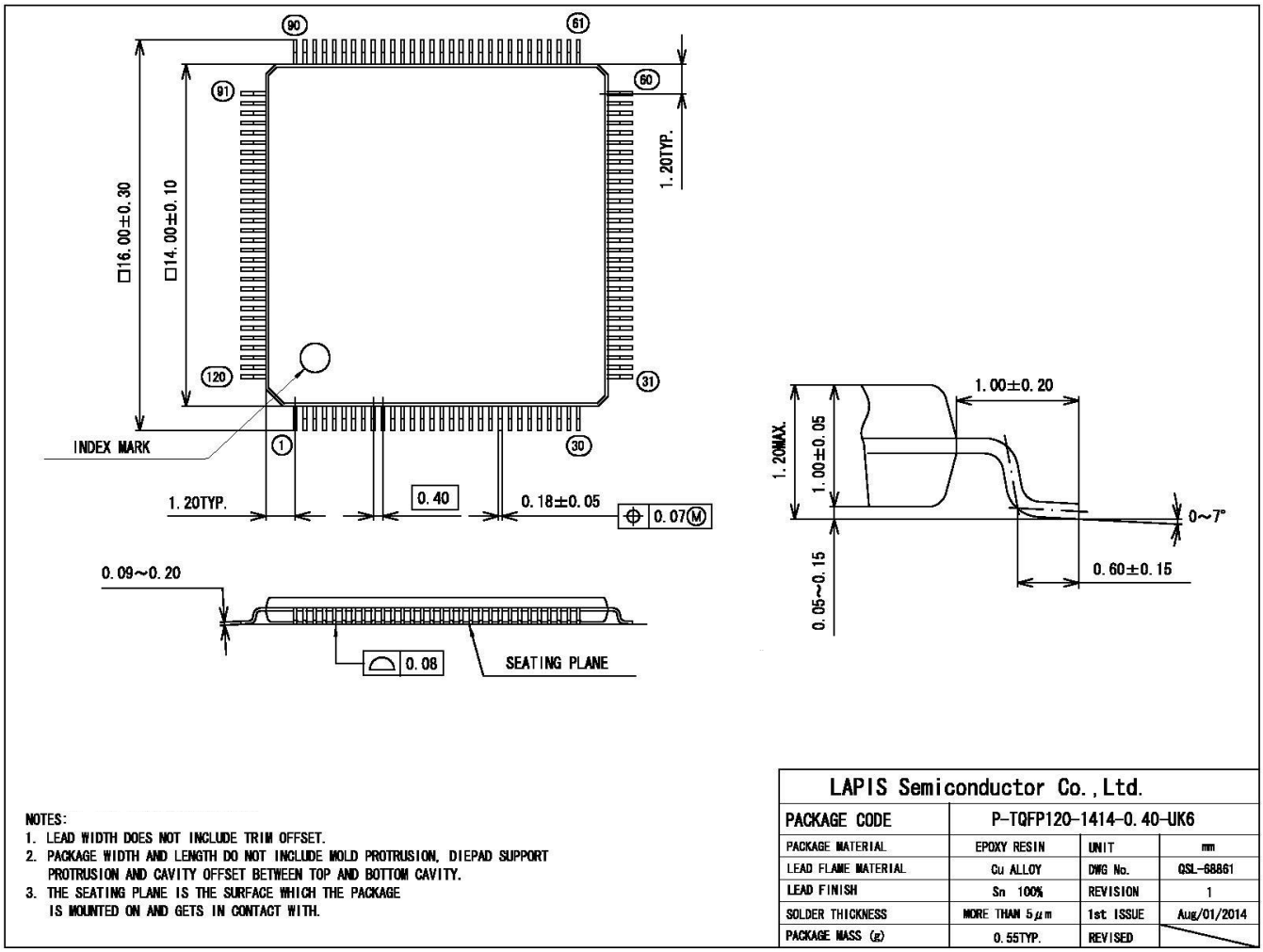
*1: Input logic circuit to determine the specified measuring conditions.

Note:

- Please have the shortest layout for the common node (wiring patterns which are connected to the external capacitors, resistors and IN0/IN1 pin), including CVR0/CVR1. Especially, do not have long wire between IN0/IN1 and RS0/RS1. The coupling capacitance on the wires may occur incorrect A/D conversion. Also, please do not have signals which may be a source of noise around the node.
- When RT0/RT1 (Thermistor and etc.) requires long wiring due to the restricted placement, please have VSS(GND) trace next to the signal.
- Please make wiring to components (capacitor, resisteor and etc.) necessory for objective measurement. Wiring to reserved components may affect to the A/D conversion operation by noise the components itself may have.

PACKAGE DIMENSIONS

(Unit: mm)



NOTES:
1. LEAD WIDTH DOES NOT INCLUDE TRIM OFFSET.
2. PACKAGE WIDTH AND LENGTH DO NOT INCLUDE MOLD PROTRUSION, DIEPAD SUPPORT PROTRUSION AND CAVITY OFFSET BETWEEN TOP AND BOTTOM CAVITY.
3. THE SEATING PLANE IS THE SURFACE WHICH THE PACKAGE IS MOUNTED ON AND GETS IN CONTACT WITH.

LAPIS Semiconductor Co.,Ltd.			
PACKAGE CODE	P-TQFP120-1414-0.40-UK6		
PACKAGE MATERIAL	EPOXY RESIN	UNIT	mm
LEAD FLAME MATERIAL	Cu ALLOY	DWG No.	QSL-68861
LEAD FINISH	Sn 100%	REVISION	1
SOLDER THICKNESS	MORE THAN 5μm	1st ISSUE	Aug/01/2014
PACKAGE MASS (g)	0.55TYP.	REVISED	

Notes for Mounting the Surface Mount Type Package

The surface mount type packages are very susceptible to heat in reflow mounting and humidity absorbed in storage. Therefore, before you perform reflow mounting, contact a ROHM sales office for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

REVISION HISTORY

Document No.	Date	Page		Description
		Previous Edition	Current Edition	
FEDL610Q411-01	Jul.17,2010	–	–	Formally edition 1
FEDL610Q411-02	Mar.23,2011	3, 4, 21	3, 4, 21	Add the explanation of ML610Q411PC.
		34	34	Replace the package dimension (Only the format is changed. Package size and material are not changed.)
FEDL610Q411-03	Apr.15,2015	All	All	Change header and footer.
		1~3 5 7 9 11 13 15 16 18~20 21 23 24 25 27	1~3 5 7 9 11 13 15 16 18~20 22 24 25 26 27	Delete ML610Q415 and ML610Q411PC
		4	4	Change from "Shipment" to "Product name ― Supported Function"
		–	21	Add CLOCK GENERATION CIRCUIT OPERATING CONDITIONS
		21	22	Change "RESET" to "Reset pulse width (P_{RST}) " and "Power-on reset activation power rise time (T_{POR}) ".
		36	36	Change description in Note.
FEDL610Q411-04	July.13,2015	14	14	Corrected a typo. -PAD No,"37" is corrected to "36". -PAD No,"36" is corrected to "35".

Notes

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